

Precision Micropower Shunt Voltage Reference in bare die form

Description

The LM4040D-4.1 is a high precision, two-terminal shunt mode, bandgap voltage reference with fixed reverse breakdown voltage of 4.096V. The device is ideal for space-critical high reliability applications with initial 1% accuracy and 150ppm/°C max temperature coefficient. A 73µA to 15mA shunt current capability with low dynamic impedance ensures stable reverse breakdown voltage accuracy over a wide current range and operating temperature. No external stabilizing capacitors are required.

Ordering Information

The following part suffixes apply:

- No suffix MIL-STD-883 /2010B Visual Inspection
- "H" MIL-STD-883 /2010B Visual Inspection + MIL-PRF-38534 Class H LAT
- "K" MIL-STD-883 /2010A Visual Inspection (Space) + MIL-PRF-38534 Class K LAT

LAT = Lot Acceptance Test.

For further information on LAT process flows see below.

www.siliconsupplies.com\quality\bare-die-lot-qualification

Supply Formats:

- Default Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape On request
- Unsawn Wafer On request
- Die Thickness <> 280µm(11 Mils) On request
- In Metal or Ceramic package On request

Features:

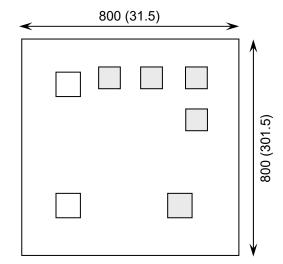
- ±1% (max) output voltage tolerance at 25°C
- 20ppm/°C typical temperature coefficient at 25°C

Rev 1.1

29/07/22

- Wide operating current range 73µA to 15mA
- No output capacitor required
- Tolerates capacitive load
- Bandgap reference corrects temperature drift
- Specified over military temperature range.

Die Dimensions in µm (mils)



Mechanical Specification

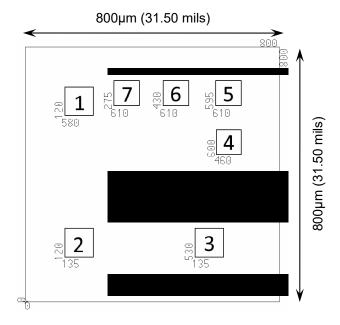
Die Size (Unsawn)	800 x 800 31.5 x 31.5	µm mils	
Minimum Bond Pad Size	90 x 90 3.54 x 3.54	µm mils	
Die Thickness	260 (±20) 10.24 (±0.8)		
Top Metal Composition	Al 1%Si 1.4µm		
Back Metal Composition	Ti/Ni/Ag 1.2µm		





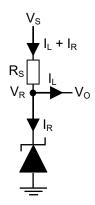
Rev 1.1 29/07/22

Pad Layout and Functions



PAD	FUNCTION	COORDINATES (µm)			
	renerien	X	Y		
1	CATHODE +	120	580		
2	ANODE -	120	135		
3	NO CONNECT	530	135		
4	NO CONNECT	600	480		
5	NO CONNECT	595	610		
6	NO CONNECT	430	610		
7	NO CONNECT	275	610		
CONNECT CHIP BACK TO GND					

Typical Application



An external series resistor (R_s) is connected between the supply voltage, V_s , and the LM4040D.

 $R_{\rm S}$ determines the current that flows through the load (I_L) and the LM4040D (I_R). Since load current and supply voltage may vary, $R_{\rm S}$ should be small enough to supply at least the minimum acceptable I_R to the LM4040D even when the supply voltage is at its minimum and the load current is at its maximum value. When the supply voltage is at its maximum and I_L is at its minimum, $R_{\rm S}$ should be large enough so that the current flowing through the LM4040D is less than 15mA.

 R_s is determined by the supply voltage, (V_s), the load and operating current, (I_L and I_R), and the LM4040D's reverse breakdown voltage, V_R .

$$R_{\rm S} = \frac{V_{\rm S} - V_{\rm R}}{I_{\rm L} + I_{\rm R}}$$





Rev 1.1 29/07/22

Absolute Maximum Ratings¹ $T_A = 25^{\circ}C$ unless otherwise stated

PARAMETER	SYMBOL	VALUE	UNIT	
Reverse Current	I _R	25	mA	
Forward Current	I _F	10	mA	
Operating Temperature Range	TJ	-55 to +150	°C	
Storage Temperature	T _{STG}	-65 to 150	°C	

1. Operation above the absolute maximum rating may cause device failure. Operation at the absolute maximum ratings, for extended periods, may reduce device reliability.

Recommended Operating Conditions T_J = 25°C unless otherwise stated

PARAMETER	SYMBOL	MIN	MAX	UNIT		
Reverse Current	I _R	0.073	15	mA		
Operating Temperature Range	-	-55 to 125		-55 to 125 °C		C°

Electrical Characteristics, T_J = 25°C unless otherwise stated

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Reverse Breakdown Voltage	V _R	I _R =100μA	-	4.096	-	V
Reverse Breakdown Voltage Tolerance ²	V _R	I _R =100μA	-	-	±41	mV
		I_{R} =100µA, T_{J} = -40 to +85°C	-	-	±81	
		I _R =100μA, T _J = -55 to +125°C	-	-	±103	
Minimum Operating	1	T _J = 25°C	-	50	73	μΑ
Current	I _{RMIN}	T _J = -55 to +125°C	-	-	78	
Average Reverse Breakdown Voltage	ΔV _R / ΔΤ	I _R =10mA	-	±30	-	ppm /°C
		I _R =1mA	-	±20	-	
		I _R =100μA	-	±20	-	
Temperature Coefficient ²		I_R =10mA, T_J = -55 to +125°C	-	-	±150	
occincient		I _R =1mA, T _J = -55 to +125°C	-	-	±150	
		I_{R} =100µA, T_{J} = -55 to +125°C	-	-	±150	
Breakdown Voltage Change with Operating Current Change ⁷	ΔV _R / ΔI _R	$I_{RMIN} \le I_R \le 1mA$	-	0.5	0.9	
		$I_{RMIN} \le I_R \le 1$ mA, $T_J = -55$ to $+125^{\circ}$ C	-	-	1.5	mV
		1mA≤ I _R ≤ 15mA	-	3	9	
		$1\text{mA} \le \text{I}_{\text{R}} \le 15\text{mA}, \text{T}_{\text{J}} = -55 \text{ to } +125^{\circ}\text{C}$	-	-	13	





Rev 1.1 29/07/22

Electrical Characteristics, T_J = 25°C unless otherwise stated

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Reverse Dynamic Impedance	Z _R	I_R = 1mA, f = 120 Hz, I_{AC} = 0.1 I_R	-	0.5	1.3	Ω
Wideband Noise	e _N	I _R =100µA, 10 Hz ≤ f ≤ 10 kHz	-	80	-	μV_{RMS}
Reverse Breakdown Voltage Long Term Stability	ΔV _R	t = 1000 hours T = 25°C ±0.1°C, I _R =100µA	-	120	-	ppm
Thermal Hysteresis	V _{HYST}	ΔT = -40 to 125°C	-	0.08	-	%

2. Reverse Breakdown Tolerance is defined as the room temperature Reverse Breakdown Voltage Tolerance $\pm[(\Delta V_R/\Delta T)(max\Delta T)(V_R)]$. Where, $\Delta V_R/\Delta T$ is the V_R temperature coefficient, max ΔT is the maximum difference in temperature from the reference point of 25°C to T_{MIN} or T_{MAX} , and V_R is the reverse breakdown voltage. 3. Load regulation is measured on pulse basis from no load to the specified load current. Output changes due to die temperature change must be taken into account separately. Thermal hysteresis is defined as the difference in voltage measured at +25°C after cycling to temperature -40°C and the 25°C measurement after cycling to temperature +125°C.

DISCLAIMER: The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Silicon Supplies Ltd hereby disclaims any and all warranties and liabilities of any kind.

LIFE SUPPORT POLICY: Silicon Supplies Ltd components may be used in life support devices or systems only with the express written approval of Silicon Supplies Ltd, if a failure of such components can reasonably be expected to cause the failure of that life support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

